LMN3612PJZF 30V N-Channel MOSFET

Features

- 30V, 5.3A, $R_{DS(ON)}$=36mΩ@V_{GS}=4.5V
- Improved dv/dt capability
- Fast switching
- Suit for 2.5V Gate Drive Applications
- Green Device Available
- SOT-23 package design

Product Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

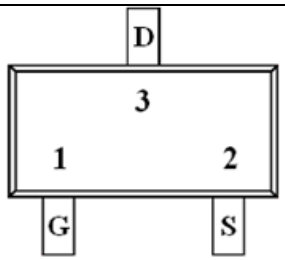
These devices are well suited for high efficiency fast switching applications.

Applications

- Notebook
- Load Switch
- LED applications

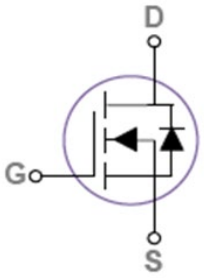
Pin Configuration

LMN3612PJZF (SOT-23)



Transparent top view

Pin	Description
1	Gate
2	Source
3	Drain



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Ordering Information

Ordering Information					
Part Number	P/N	PKG code	Pb Free code	Package	Quantity
LMN3612PJZF	LMN3612P	JZ	F	SOT-23	3000 PCS

Marking Information

Marking Information		
Part Marking	Part Number	LFC code
PXWMM	P	XWMM

Absolute Maximum Ratings

(T_C=25ºC Unless otherwise noted)

Symbol	Parameter		Typical	Unit
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		±12	V
I_D	Continuous Drain Current	T_A=25℃	5.3	A
		T_C=100℃	3.4	
I_{DM}	Pulsed Drain Current[2]		21.2	A
P_D	Power Dissipation (Tc=25℃)		1.56	W
	Power Dissipation (Derate above 25℃)		0.012	
T_J	Operating Junction Temperature		-55 to +150	℃
T_{STG}	Storage Temperature Range		-55 to +150	℃
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient[1]		80	℃/W

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Electrical Characteristics

(T_C=25ºC Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	30			V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃, I_D=1mA		0.06		V/℃
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	0.4	0.6	0.9	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient			-3		mV/℃
I_{GSS}	Gate Leakage Current	V_{DS}=0V, V_{GS}=±12V			±100	nA
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V, V_{GS}=0V			1	uA
		V_{DS}=24V, V_{GS}=0V, T_J=125℃			10	
I_S	Continuous Source Current	V_G=V_D=0V, Force Current			5.3	A
I_{SM}	Pulsed Source Current				21.2	
$R_{DS(on)}$	Drain-Source On-Resistance	V_{GS}=4.5V, I_D=4A		31	36	mΩ
		V_{GS}=2.5V, I_D=3A		36	45	
g_{FS}	Forward Transconductance	V_{DS}=10V, I_D=3A		7		S
V_{SD}	Diode Forward Voltage	I_S=1A, V_{GS}=0V			1	V
Dynamic						
Q_g	Total Gate Charge[2,3]	V_{DS}=10V, V_{GS}=4.5V, I_D=4A		8.4	12	nC
Q_{gs}	Gate-Source Charge[2,3]			1	2	
Q_{gd}	Gate-Drain Charge[2,3]			2.2	4	
C_{iss}	Input Capacitance	V_{DS}=10V, V_{GS}=0V, f=1MHz		695	1000	pF
C_{oss}	Output Capacitance			45	65	
C_{rss}	Reverse Transfer Capacitance			36	50	
$t_{d(on)}$	Turn-On Time[2,3]	V_{DD}=10V, I_D=1A, V_{GS}=4.5V, R_G=25Ω		4.5	9	ns
t_r				13	25	
$t_{d(off)}$	Turn-Off Time[2,3]			27	51	
t_f				8.3	16	
R_g	Gate Resistance	V_{DS}=0V, V_{GS}=0V, f=1MHz		1.5	3	Ω

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤300us , duty cycle ≤2%.
3. Essentially independent of operating temperature.

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Typical Performance Characteristics

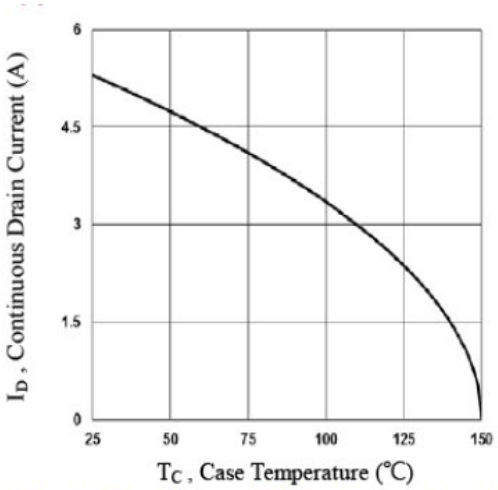

Fig.1 Continuous Drain Current vs. T_c

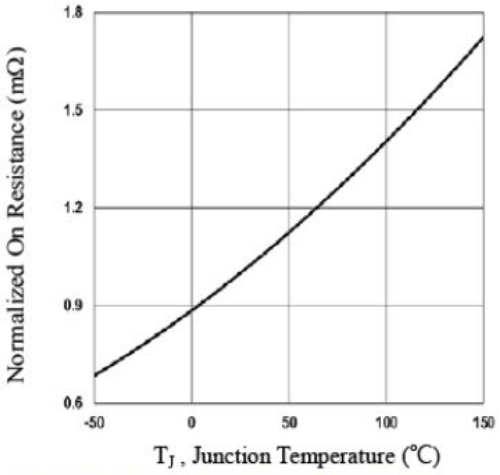

Fig.2 Normalized RDSON vs. T_J

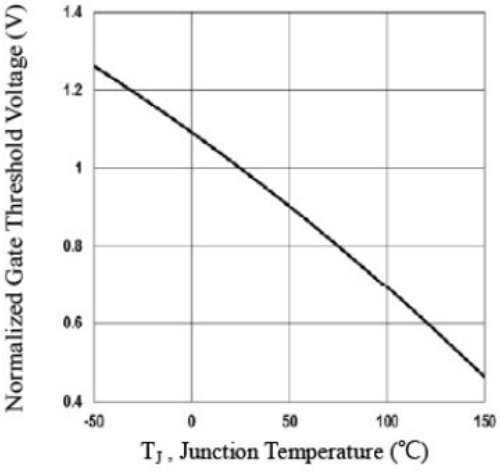

Fig.3 Normalized V_{th} vs. T_J

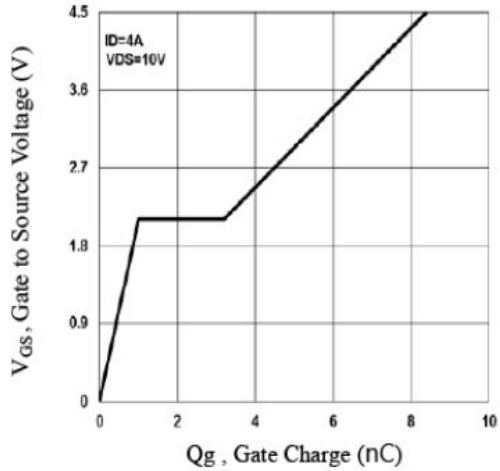

Fig.4 Gate Charge Waveform

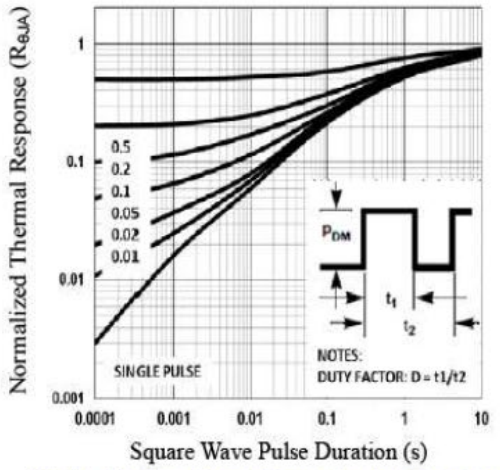

Fig.5 Normalized Transient Impedance

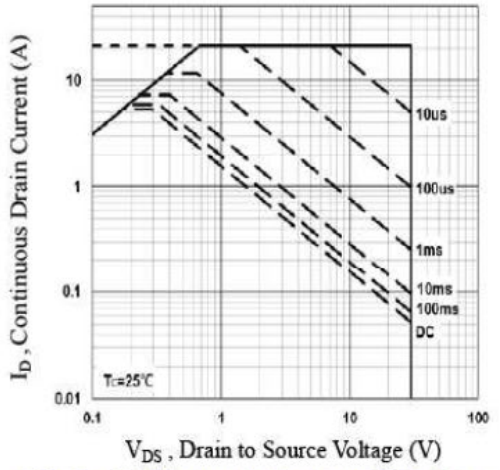

Fig.6 Maximum Safe Operation Area

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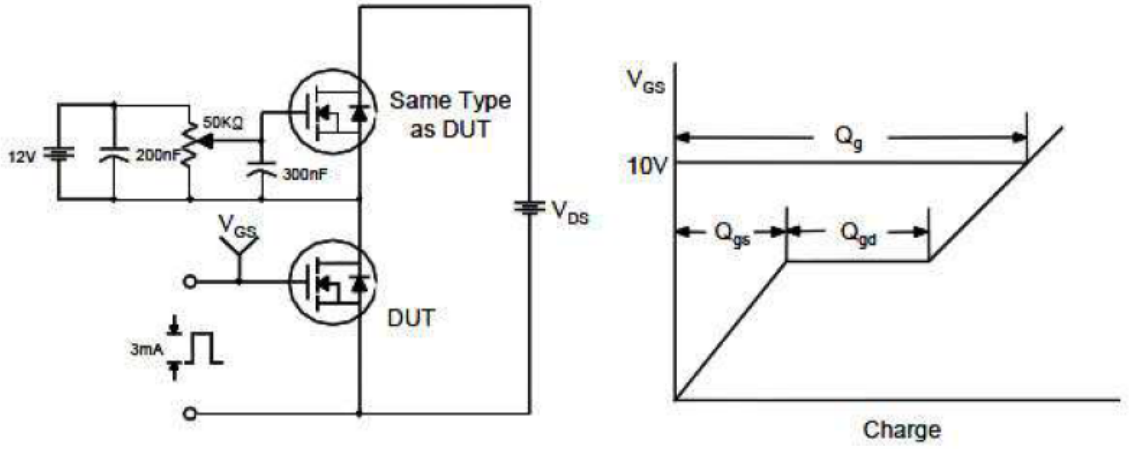
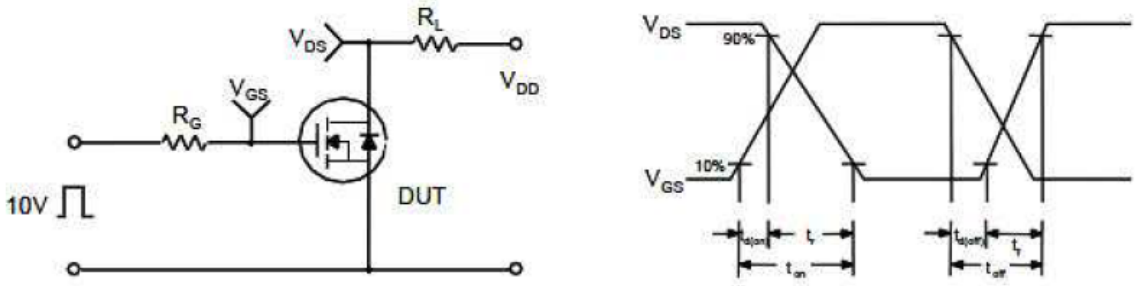
Typical Performance Characteristics(continue)

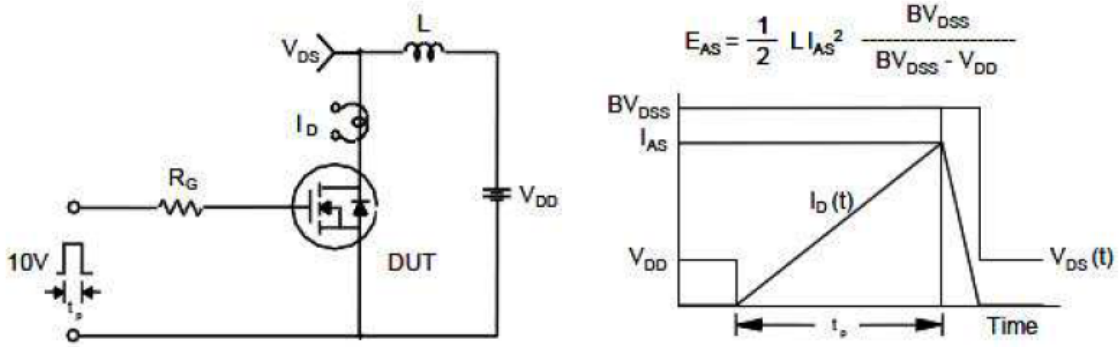
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



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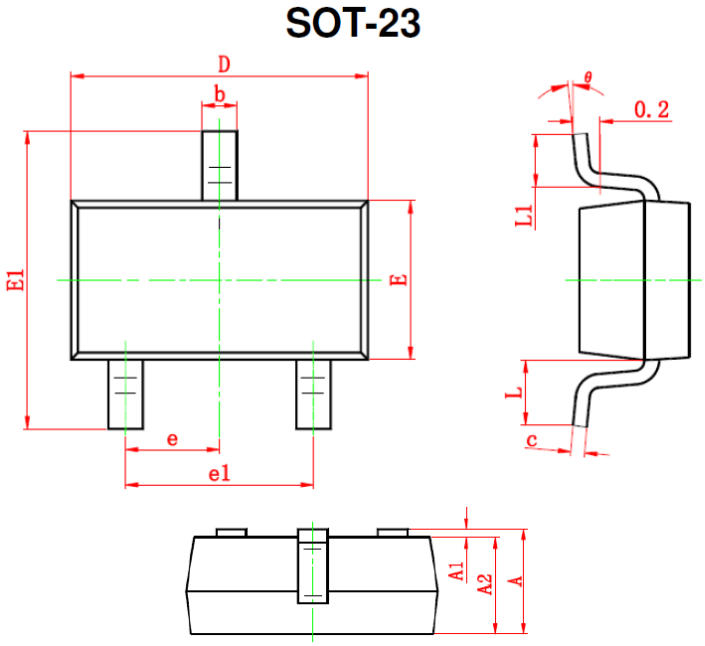
Package Dimension:



Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.90	1.20	0.035	0.043
A1	0.00	0.10	0.000	0.004
A2	0.90	1.10	0.035	0.039
b	0.30	0.50	0.012	0.020
c	0.08	0.15	0.003	0.006
D	2.80	3.00	0.110	0.118
E	1.20	1.40	0.047	0.055
E1	2.25	2.55	0.089	0.10
e	0.95 TYP		0.037 TYP	
e1	1.80	2.00	0.071	0.079
L	0.55 REF		0.022 REF	
L1	0.30	0.50	0.012	0.020
θ	0°	8°	0°	8°

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